IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Comp © Copyright 2005. international and Pa	<b>position De</b> IPC, Bannock an-American c	<b>claration</b> burn, Illinois. <i>A</i> opyright conve	all rights reserved untions.	This clevel					vithin the manufactu level materials for w					
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Tyl http://www.ipc.org/IPC-175x Distribut				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	ials and Mfg Information			
upplier Infor	mation														
Company name*			Company unique ID			Uı	Unique ID Authority					Response Date*			
nsemi											2023-06-08				
Contact Name			Title - Contact			Pł	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards		Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*		Title - Representative			Pł	Phone - Representative*				Email - Representative*				
Product-Env-Stev	wards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
Reques	uester Item Number Mfr Iter		m Number Mfr Item Name			E	Effective Date	Version	Version Manufactu		,	Weight*	UOM	Unit Type	
		MHz a		3.3 V, Crystal to 25 MHz, 100 MHz, 125 MHz and 200 MHz Dual HCSL Clock Generator		25 2	2023-06-08		PI	PH1		15.4	mg	Each	
Ianufacturing	g Proccess Informa	ation						•							
Terminal Plating / Grid Array Material		Terminal Base Alloy J-ST		J-STD-020 MSL Ratii	ng	Peak Proc	Process Body Temperature Max Time at Peak		Temperature Number of Re		per of Reflow Cyc	eles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		C 30		seconds 3					
omments				·					•						
vel 1 - maximum	ı time at peak temperat	ture during so	ldering is 10-3	0 seconds											
or more informa	tion regarding materia	l composition	please refer to	page 3		•									

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correction to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale a											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.0	mg	Supplier	Silicon (Si)	7440-21-3		2	mg
Die Attach	1.32	mg	Supplier	Silver (Ag)	7440-22-4		0.99	mg
			Supplier	Epoxy resins	129915-35-1		0.33	mg
Lead Frame	20.76	mg	Supplier	Iron (Fe)	7439-89-6		0.3944	mg
			Supplier	Copper (Cu)	7440-50-8		20.3656	mg
Mold Compound-Black	19.0	mg		Epoxy resin	proprietary data		0.95	mg
			Supplier	Phenolic Resin	Proprietary Data		0.95	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.38	mg
			Supplier	Carbon Black (C)	1333-86-4		0.095	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.625	mg
Plating	2.12		Supplier	Palladium (Pd)	7440-05-3		0.1611	mg
			В	Nickel (Ni)	7440-02-0		1.9292	mg
			Supplier	Gold (Au)	7440-57-5		0.0297	mg
Wire Bond - Au	0.2	mg	Supplier	Gold (Au)	7440-57-5		0.2	mg